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DOCUMENT-IDENTIFIER: US 6413321 B1

TITLE: Method and apparatus for reducing particle contamination on wafer backside during CVD process

Brief Summary Text (8):

Anti reflective coatings (ARC) formed by plasma-enhanced chemical vapor deposition (PECVD) have been widely used to control CD during photolithography processing steps by suppressing over 99% of light reflected from a substrate. In general however, wafers that have received an ARC film must generally be subjected to additional processing steps in order to remove particles on the wafer backside before the wafer is exposed to lithography steps.

↑
patterning (clv)